



Rear I/O

Features

- Fanless system with IBASE MB230 customized board
- 9th/8th Gen Intel® Core™ i7/i5/i3 Desktop Processors
- Dual SIM slots supports WWAN redundancy
- 4x RJ45 Gigabit Ethernet port (2x Supports 802.3at PoE+) 3x M.2 (B-Key/E-Key/M-Key)
- Supports Over/Under/Reverse voltage protection
- iSMART, iAMT (11.6), TPM (2.0)

Specifications

System Mainboard	MB230AF with Intel® Q370 PCH MB230AF-P with Intel® Q370 PCH (supports PCI-E function for M.2 (B-KEY))
CPU Type	9th/8th Gen Intel® Core™ i7/i5/i3 Desktop Processors
System Speed	Up to 4.0 GHz
Memory	2x DDR4-2666/2400 SO-DIMM, Max. 32GB
Construction	Aluminum & steel
Chassis Color	Silver + Gray (Aluminum)
Front Panel External I/O	2x RS232/422/485 port for COM#1~COM#2 2x RS232 ports for COM#3~COM#4 1x DisplayPort (1.2) 2x RJ45 Gigabit Ethernet port (Supports 802.3at PoE+) 1x 5-pins DC-in terminal block type for 12V or 18V~24V 2x Antenna holes
Rear Panel External I/O	1x DVI-D + HDMI(1.4) 4x USB 3.1 ports 2x Antenna holes 2x RJ45 Gigabit Ethernet port+Dual USB 3.1 stack ports 1x Red HDD LED 1x power button with Green LED indicator 1x 2-pin terminal block 2x SIM card
Others	1x M.2 (E-Key) slot
Storage / M.2	1x 2.5 HDD/SSD, 2x M.2 (B-Key, M-Key) *M-key Supports NVMe SSD
Mounting	Desktop & wall mount
Dimensions	210mm(W) x 285mm(D) x 77mm(H)
Weight	4kg
Operating Temperature	-20°C to 70°C (-4°F~158°F) (for 35W CPU)
Storage Temperature	-20°C~80°C (-4°F~176°F)

Relative Humidity	10~95%, non-condensing @60 degree C
Vibration	Operating : 3Grms / 5~500Hz
Shock	Operating : 20G / 11ms Non-operating : 40G / 11ms
Certification	CE/ FCC Class A/ LVD

Ordering Information

AMI230AF (Supports SIERRA module)	Fanless box System with MB230AF, w/ Intel® Core™ i7/i5/i3 desktop Processor, 4x COM, 1x 8GB memory, 1x 2.5" 64GB MLC industrial-grade SSD, w/o power adaptor
AMI230AF-P	Fanless box System with MB230AF-P, w/ Intel® Core™ i7/i5/i3 desktop Processor, 4x COM, 1x 8GB memory, 1x 2.5" 64GB MLC industrial-grade SSD, w/o power adaptor
270W Power Adaptor Kit (optional)	270W (24V@11.25A) power adaptor kit Compatible with IEC62368-1/EN62368-1
Optional Accessories	Global 4G antenna kit for Sierra Wireless EM7565 module, M.2 (M-KEY 2280) Thermal kit



Backplane Systems Technology

Backplane Systems Technology Pty Ltd

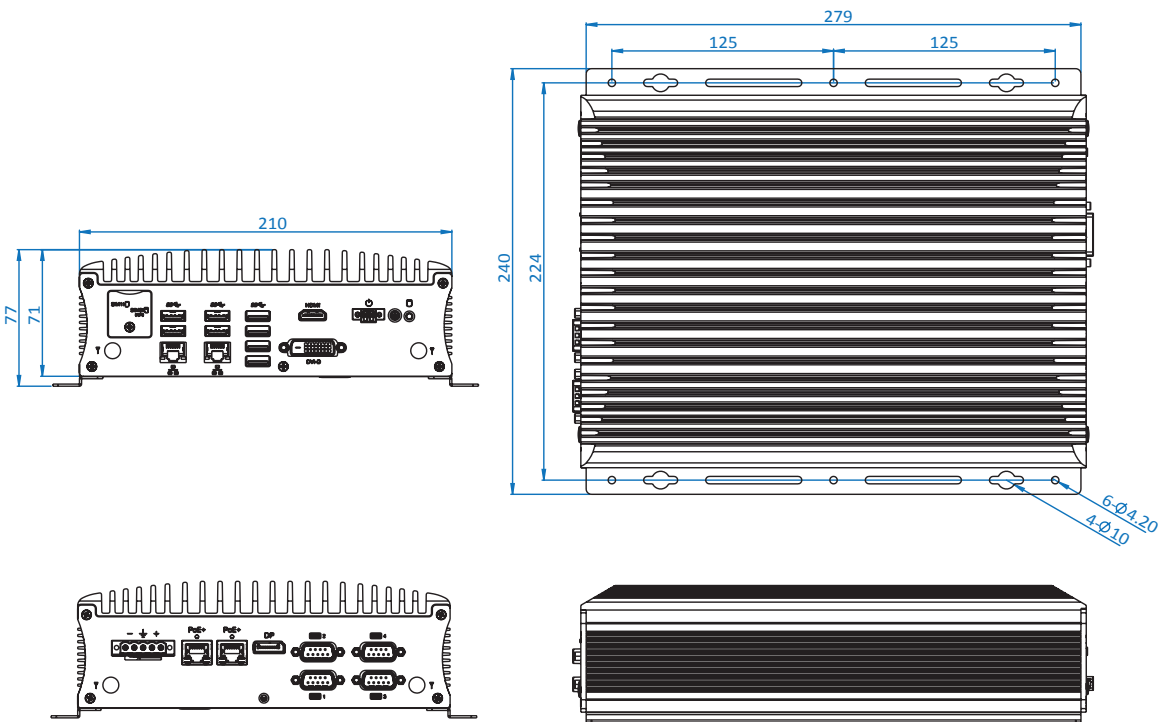
TEL 02 9457 6400
sales@backplane.com.au
www.backplane.com.au

Proudly Australian-Owned Since 1989

Recommended Processor list

Model	TDP	Base Freq	Turbo Freq	Cache	Cores / Threads
i7-9700TE	35W	1.8 GHz	3.8 GHz	12M	8/8
i7-8700T	35W	2.4 GHz	4.0 GHz	12M	6/12
i5-9500TE	35W	2.2 GHz	3.6 GHz	9M	6/6
i5-8500T	35W	2.1 GHz	3.5 GHz	9M	6/6
i3-9100TE	35W	2.2 GHz	3.2 GHz	6M	4/4
i3-8100T	35W	3.1 GHz	N/A	6M	4/4
G5400T	35W	3.1 GHz	N/A	4M	2/4
G4900T	35W	2.9 GHz	N/A	2M	2/2

Dimensions and Drawing



Backplane Systems
Technology Pty Ltd

TEL 02 9457 6400
sales@backplane.com.au
www.backplane.com.au

Proudly Australian-Owned Since 1989

Remarks: 1. Specifications are subject to change without prior notice. 2. ODM/OEM is available.

- 1 AGS Series
- 2 AMS Series
- 3 AMI Series
- 4 CMI Series
- 5 ASB Series
- 6 CSB Series